



flowPIM E2

1200 V / 32 mΩ

Topology features

- Converter+Inverter
- Open Emitter configuration
- SiC MOSFET
- Temperature sensor

Component features

- High Blocking Voltage with low drain source on state resistance
- High speed SiC-MOSFET technology
- Resistant to Latch-up

Housing features

- Base isolation: Al₂O₃
- Convex shaped substrate for superior thermal contact
- Compact housing
- CTI600 housing material
- Thermo-mechanical push-and-pull force relief
- Press-fit pin
- Reliable cold welding connection

Target applications

- Embedded Drives
- General Purpose Drives
- Heat Pumps
- HVAC
- Industrial Drives

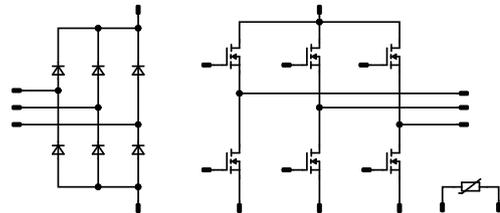
Types

- 10-EY12PNA032ME02-L188C03T

flow E2 12 mm housing



Schematic





Vincotech

10-EY12PNA032ME02-L188C03T
datasheet

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Inverter Switch				
Drain-source voltage	V_{DSS}		1200	V
Drain current (DC current)	I_D	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	39	A
Peak drain current	I_{DM}	t_p limited by T_{jmax}	120	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	74	W
Gate-source voltage	V_{GSS}		-4 / 15	V
		dynamic	-8 / 19	
Maximum Junction Temperature	T_{jmax}		175	°C

Rectifier Diode

Peak repetitive reverse voltage	V_{RRM}		1600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	58	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, $t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	400	A
Surge current capability	I^2t		800	A ² s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	68	W
Maximum junction temperature	T_{jmax}		150	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...+($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6000	V
Isolation voltage	V_{isol}	AC Voltage $t_p = 1\text{ min}$	2500	V
Creepage distance			>12,7	mm
Clearance			8,97	mm
Comparative Tracking Index	CTI		≥ 200	

*100 % tested in production



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Inverter Switch

Static

Drain-source on-state resistance	$r_{DS(on)}$		15		40	25 125 150	22,4	34,2 42,1 46,4	41,6 ⁽¹⁾	mΩ
Gate-source threshold voltage	$V_{GS(th)}$		0		0,0115	25	1,8	2,5	3,6	V
Gate to Source Leakage Current	I_{GSS}		15	0		25		10	250	nA
Zero Gate Voltage Drain Current	I_{DSS}		0	1200		25		1	19	μA
Internal gate resistance	r_g							1,7		Ω
Gate charge	Q_g		-4/15	800	40	25		118		nC
Short-circuit input capacitance	C_{iss}	$f = 100$ kHz	0	1000	0	25		3357		pF
Short-circuit output capacitance	C_{oss}							129		
Reverse transfer capacitance	C_{rss}							8		
Diode forward voltage	V_{SD}		0		20	25		4,6		V

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,28		K/W
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10-EY12PNA032ME02-L188C03T
datasheet

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		
Dynamic										
Turn-on delay time	$t_{d(on)}$	$R_{gon} = 16 \Omega$ $R_{goff} = 16 \Omega$	-4/15	600	30	25		45,83		ns
						125		40,77		
						150		39,74		
Rise time	t_r					25		35,19		
						125		30,84		ns
						150		30,3		
Turn-off delay time	$t_{d(off)}$					25		100,65		
						125		110,93		ns
						150		113,59		
Fall time	t_f					25		14,82		
						125		16		ns
						150		16,29		
Turn-on energy (per pulse)	E_{on}	$Q_{rFWD}=0,208 \mu C$ $Q_{tFWD}=0,439 \mu C$ $Q_{rFWD}=0,537 \mu C$				25		0,891		mWs
						125		0,954		
						150		1,01		
Turn-off energy (per pulse)	E_{off}					25		0,288		mWs
						125		0,287		
						150		0,285		
Peak recovery current	I_{RRM}					25		8,91		A
						125		14,6		
						150		17,24		
Reverse recovery time	t_{rr}					25		52,58		ns
						125		44,37		
						150		45,78		
Recovered charge	Q_r	$di/dt=804 A/\mu s$ $di/dt=932 A/\mu s$ $di/dt=1029 A/\mu s$				25		0,208		μC
						125		0,439		
						150		0,537		
Reverse recovered energy	E_{rec}					25		0,045		mWs
						125		0,107		
						150		0,132		
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25		433,16		A/ μs
						125		901,24		
						150		1315,15		



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Rectifier Diode

Static

Forward voltage	V_F				35	25 125 150		1,09 1,02 1,02	1,5 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 1600$ V				25 150			100 2000	μA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,03		K/W
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Thermistor

Static

Rated resistance	R					25		5		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 499$ Ω				100	3,2		3,3	%
Power dissipation	P					25		130		mW
Power dissipation constant	d					25		1,3		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %						3380		K
Vincotech Thermistor Reference									V	

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.

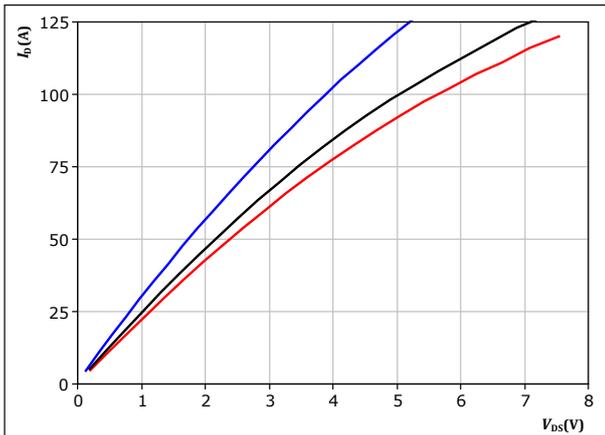


Inverter Switch Characteristics

figure 1. MOSFET

Typical output characteristics

$$I_D = f(V_{DS})$$

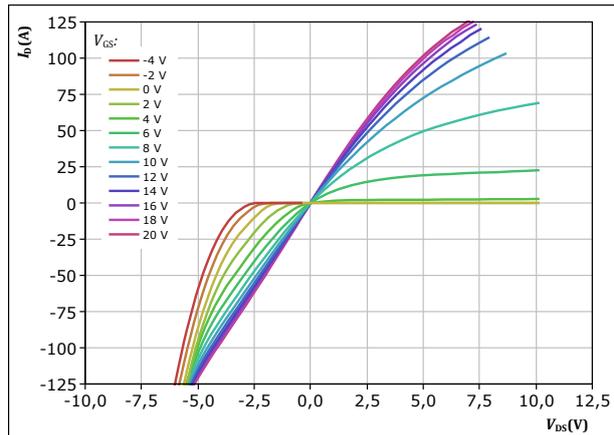


$t_p = 250 \mu s$
 $V_{GS} = 14 V$
 $T_j:$ 25 °C, 125 °C, 150 °C

figure 2. MOSFET

Typical output characteristics

$$I_D = f(V_{DS})$$

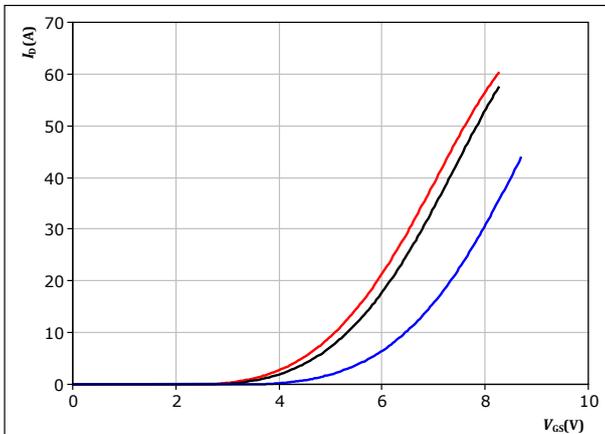


$t_p = 250 \mu s$
 $T_j = 150 \text{ }^\circ\text{C}$
 V_{GS} from -4 V to 20 V in steps of 2 V

figure 3. MOSFET

Typical transfer characteristics

$$I_D = f(V_{GS})$$

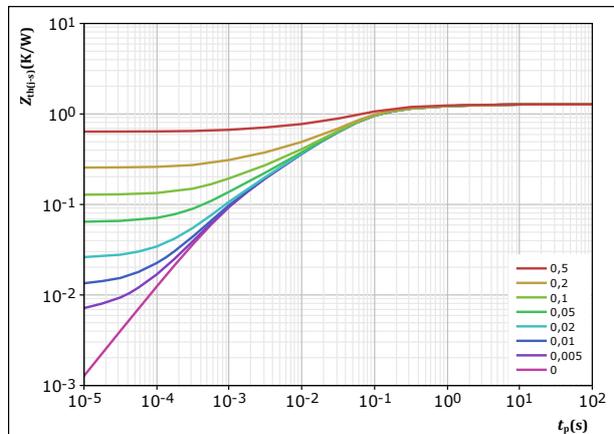


$t_p = 250 \mu s$
 $V_{DS} = 10 V$
 $T_j:$ 25 °C, 125 °C, 150 °C

figure 4. MOSFET

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 1,276 \text{ K/W}$
MOSFET thermal model values

R (K/W)	τ (s)
6,59E-02	2,75E+00
1,80E-01	3,21E-01
7,28E-01	5,55E-02
2,13E-01	8,37E-03
8,96E-02	1,01E-03

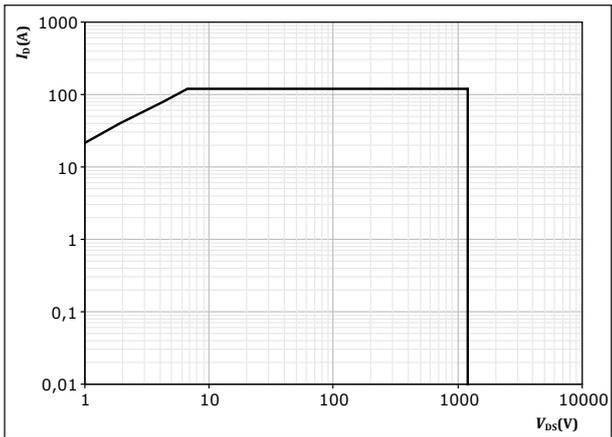


Inverter Switch Characteristics

figure 5. MOSFET

Safe operating area

$$I_D = f(V_{DS})$$



$D =$ single pulse

$T_s = 80$ °C

$V_{GS} = 14$ V

$T_j = T_{jmax}$



Rectifier Diode Characteristics

figure 6. Rectifier

Typical forward characteristics

$$I_F = f(V_F)$$

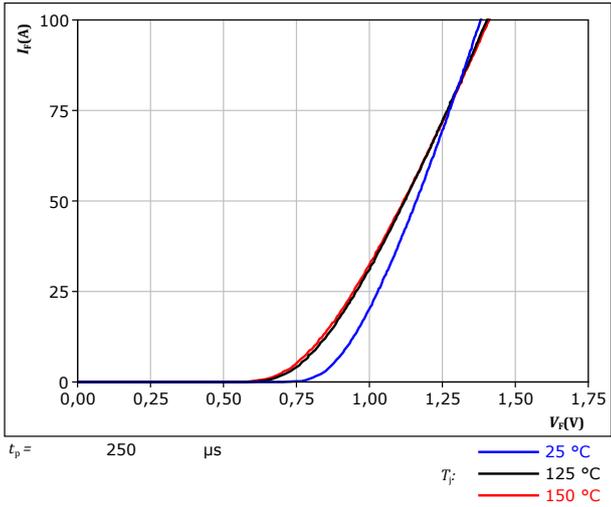
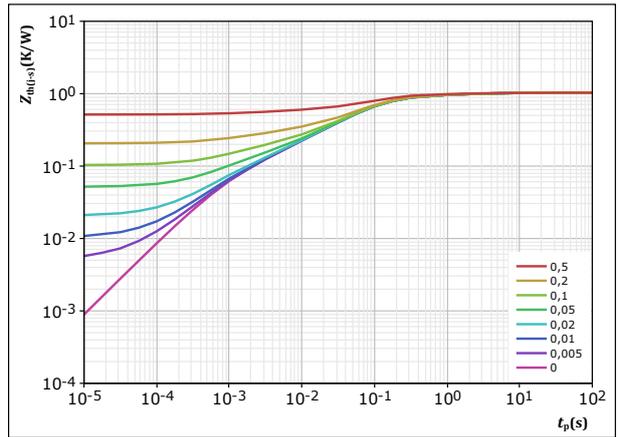


figure 7. Rectifier

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = \frac{t_p}{T}$
 $R_{th(j-s)} = 1,032 \text{ K/W}$
 Rectifier thermal model values

R (K/W)	τ (s)
4,86E-02	5,67E+00
1,31E-01	6,68E-01
5,24E-01	9,95E-02
1,97E-01	3,35E-02
8,14E-02	4,54E-03
4,98E-02	8,29E-04

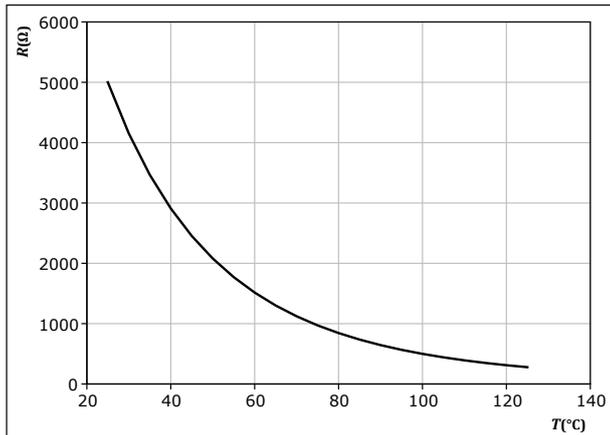


Thermistor Characteristics

figure 8. Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$

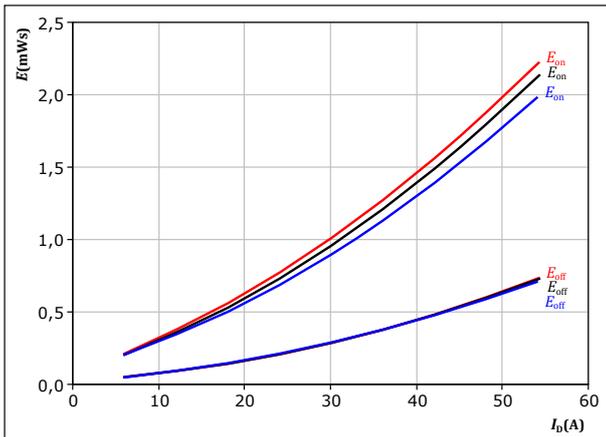




Inverter Switching Characteristics

figure 9. MOSFET

Typical switching energy losses as a function of drain current
 $E = f(I_D)$



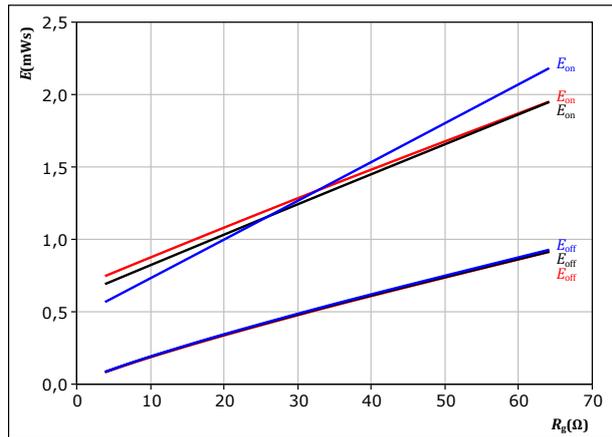
With an inductive load at

$V_{DS} = 600 \text{ V}$
 $V_{GS} = -4/15 \text{ V}$
 $R_{gon} = 16 \ \Omega$
 $R_{goff} = 16 \ \Omega$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 10. MOSFET

Typical switching energy losses as a function of MOSFET turn on gate resistor
 $E = f(R_g)$



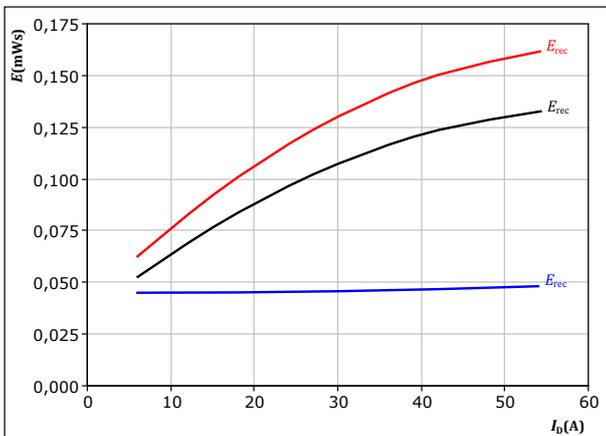
With an inductive load at

$V_{DS} = 600 \text{ V}$
 $V_{GS} = -4/15 \text{ V}$
 $I_D = 30 \text{ A}$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 11. MOSFET

Typical reverse recovered energy loss as a function of drain current
 $E_{rec} = f(I_D)$



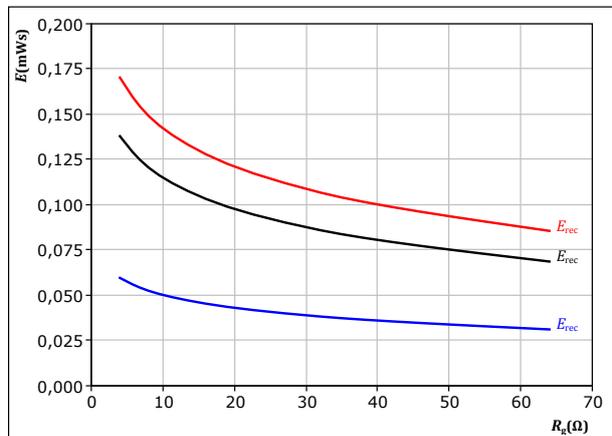
With an inductive load at

$V_{DS} = 600 \text{ V}$
 $V_{GS} = -4/15 \text{ V}$
 $R_{gon} = 16 \ \Omega$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 12. MOSFET

Typical reverse recovered energy loss as a function of MOSFET turn on gate resistor
 $E_{rec} = f(R_g)$



With an inductive load at

$V_{DS} = 600 \text{ V}$
 $V_{GS} = -4/15 \text{ V}$
 $I_D = 30 \text{ A}$

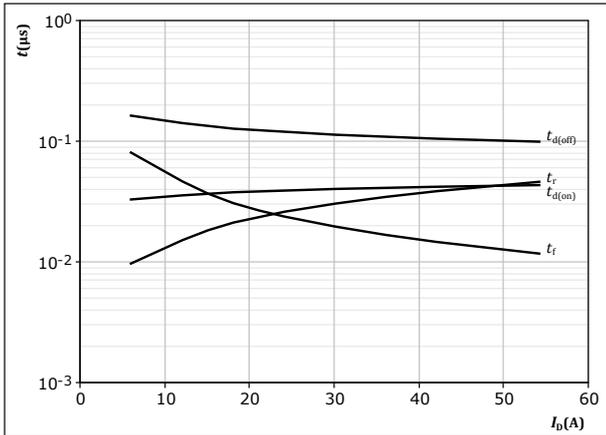
T_j : — 25 °C
— 125 °C
— 150 °C



Inverter Switching Characteristics

figure 13. MOSFET

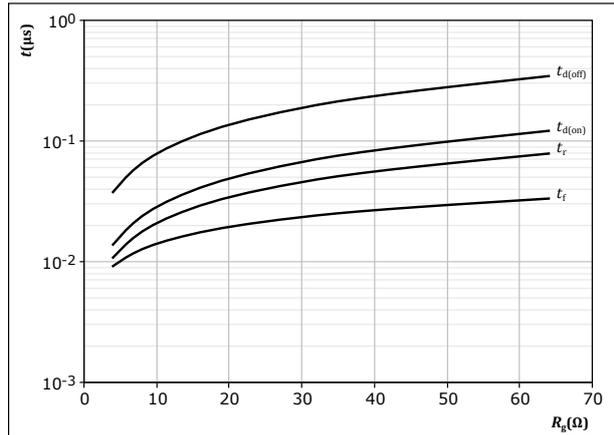
Typical switching times as a function of drain current
 $t = f(I_D)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{DS} = 600 \text{ V}$
 $V_{GS} = -4/15 \text{ V}$
 $R_{gon} = 16 \text{ } \Omega$
 $R_{goff} = 16 \text{ } \Omega$

figure 14. MOSFET

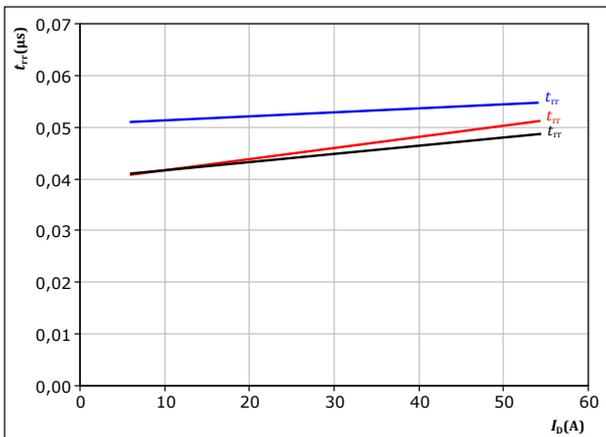
Typical switching times as a function of MOSFET turn on gate resistor
 $t = f(R_g)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{DS} = 600 \text{ V}$
 $V_{GS} = -4/15 \text{ V}$
 $I_D = 30 \text{ A}$

figure 15. MOSFET

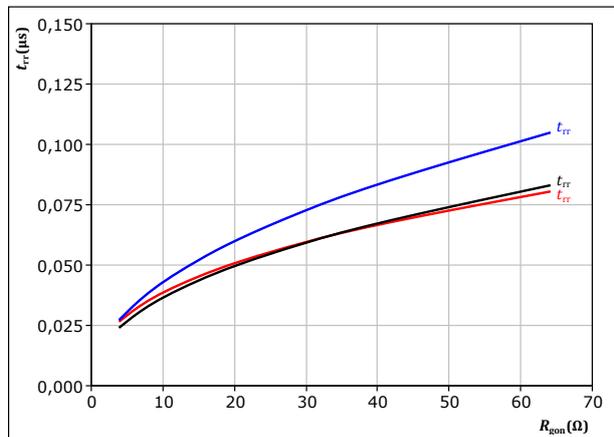
Typical reverse recovery time as a function of drain current
 $t_{rr} = f(I_D)$



At $V_{DS} = 600 \text{ V}$
 $V_{GS} = -4/15 \text{ V}$
 $R_{gon} = 16 \text{ } \Omega$
 $T_j:$ — 25 °C
— 125 °C
— 150 °C

figure 16. MOSFET

Typical reverse recovery time as a function of MOSFET turn on gate resistor
 $t_{rr} = f(R_{gon})$



At $V_{DS} = 600 \text{ V}$
 $V_{GS} = -4/15 \text{ V}$
 $I_D = 30 \text{ A}$
 $T_j:$ — 25 °C
— 125 °C
— 150 °C

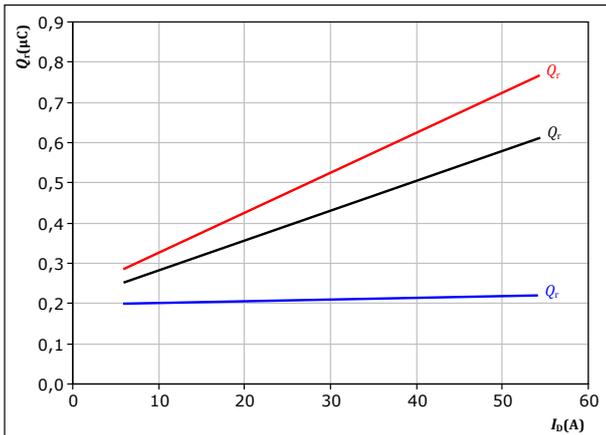


Inverter Switching Characteristics

figure 17. MOSFET

Typical recovered charge as a function of drain current

$$Q_r = f(I_D)$$



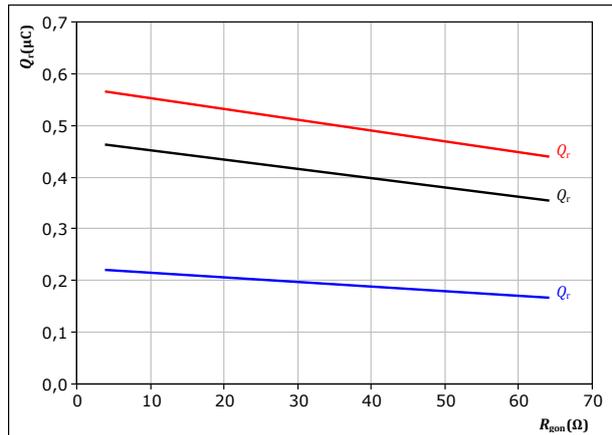
At $V_{DS} = 600$ V
 $V_{GS} = -4/15$ V
 $R_{gson} = 16$ Ω

T_j : — 25 °C
 — 125 °C
 — 150 °C

figure 18. MOSFET

Typical recovered charge as a function of MOSFET turn on gate resistor

$$Q_r = f(R_{gson})$$



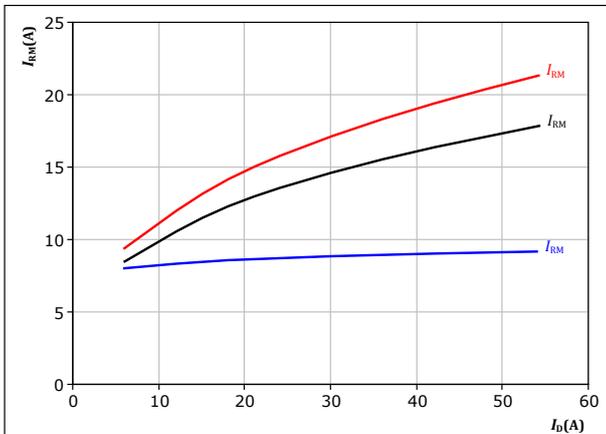
At $V_{DS} = 600$ V
 $V_{GS} = -4/15$ V
 $I_D = 30$ A

T_j : — 25 °C
 — 125 °C
 — 150 °C

figure 19. MOSFET

Typical peak reverse recovery current as a function of drain current

$$I_{RM} = f(I_D)$$



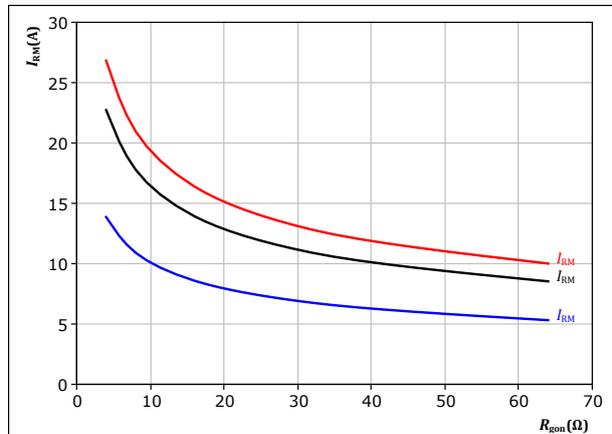
At $V_{DS} = 600$ V
 $V_{GS} = -4/15$ V
 $R_{gson} = 16$ Ω

T_j : — 25 °C
 — 125 °C
 — 150 °C

figure 20. MOSFET

Typical peak reverse recovery current as a function of MOSFET turn on gate resistor

$$I_{RM} = f(R_{gson})$$



At $V_{DS} = 600$ V
 $V_{GS} = -4/15$ V
 $I_D = 30$ A

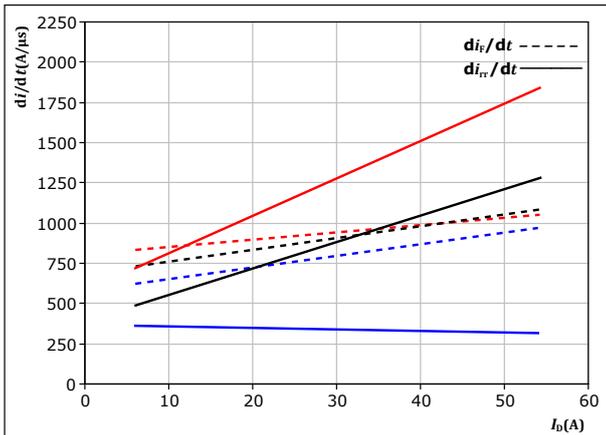
T_j : — 25 °C
 — 125 °C
 — 150 °C



Inverter Switching Characteristics

figure 21. MOSFET

Typical rate of fall of forward and reverse recovery current as a function of drain current
 $di_f/dt, di_{rr}/dt = f(I_D)$

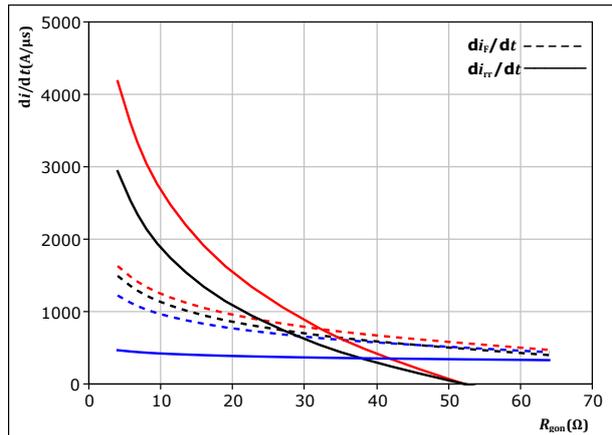


At $V_{DS} = 600$ V
 $V_{GS} = -4/15$ V
 $R_{g(on)} = 16$ Ω

T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 22. MOSFET

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_{rr}/dt = f(R_{g(on)})$

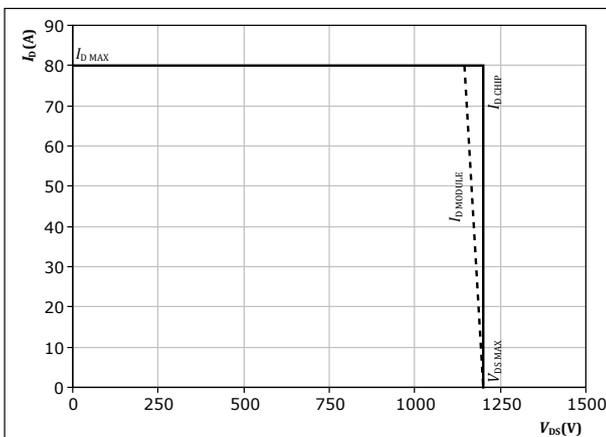


At $V_{DS} = 600$ V
 $V_{GS} = -4/15$ V
 $I_D = 30$ A

T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 23. MOSFET

Reverse bias safe operating area
 $I_D = f(V_{DS})$



At $T_j = 150$ °C
 $R_{g(on)} = 16$ Ω
 $R_{g(off)} = 16$ Ω



Inverter Switching Definitions

figure 24. MOSFET

Turn-off Switching Waveforms & definition of t_{doff} t_{Eoff} (t_{Eoff} = integrating time for E_{off})

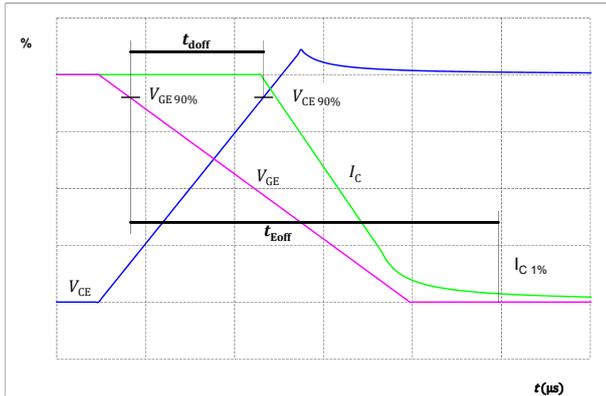


figure 25. MOSFET

Turn-on Switching Waveforms & definition of t_{don} t_{Eon} (t_{Eon} = integrating time for E_{on})

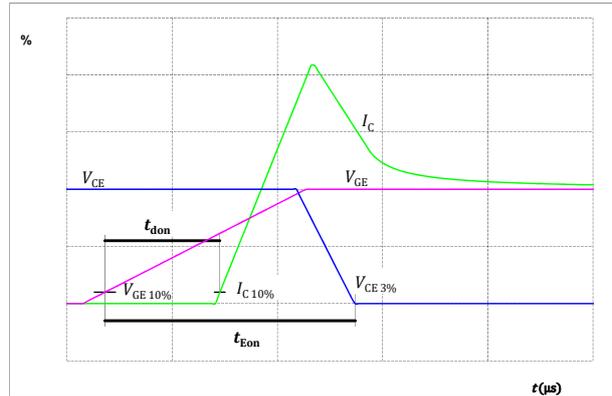


figure 26. MOSFET

Turn-off Switching Waveforms & definition of t_f

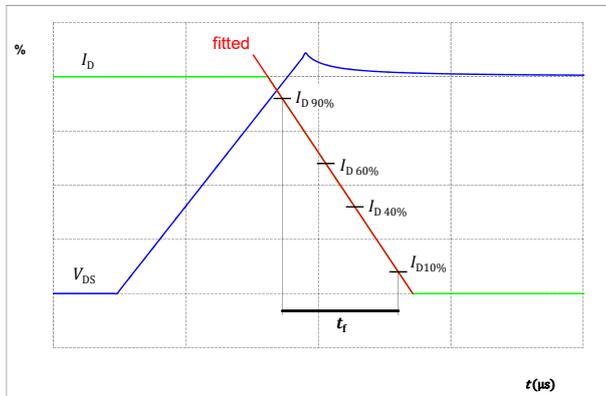
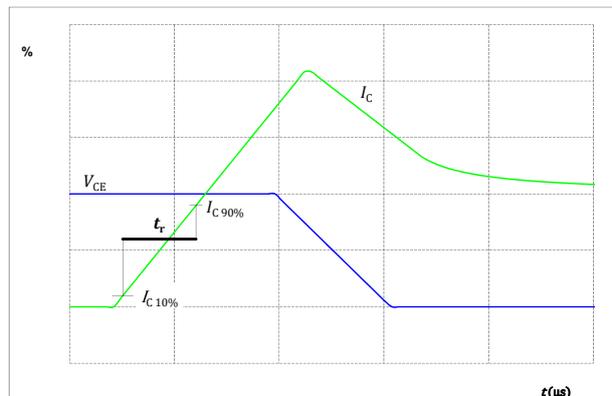


figure 27. MOSFET

Turn-on Switching Waveforms & definition of t_r





Inverter Switching Definitions

figure 28. FWD

Turn-off Switching Waveforms & definition of t_{tr}

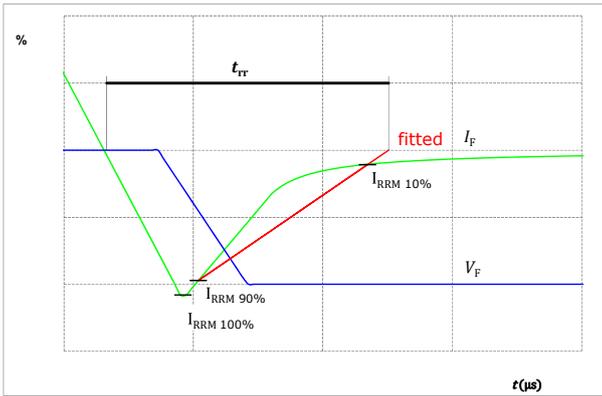


figure 29. FWD

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)

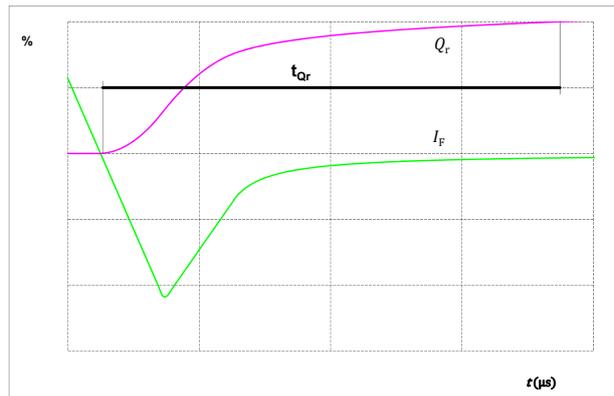
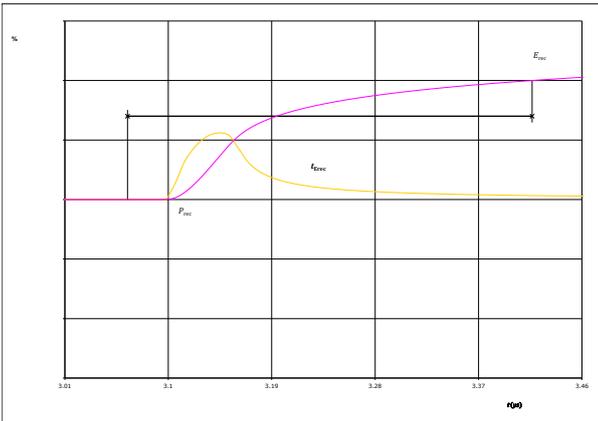


figure 30. FWD

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec} = integrating time for E_{rec})





10-EY12PNA032ME02-L188C03T

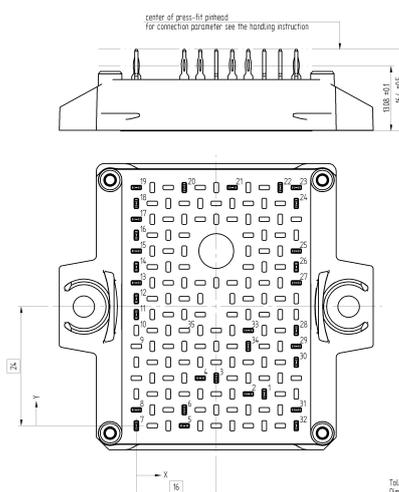
datasheet

Vincotech

Ordering Code	
Version	Ordering Code
Without thermal paste	10-EY12PNA032ME02-L188C03T
With thermal paste (3,4 W/mK, PSX-P7)	10-EY12PNA032ME02-L188C03T-/3/

Marking						
	Text	Name NN-NNNNNNNNNNNNNN- TTTTTVV	Date code WWYY	UL & VIN UL VIN	Lot LLLLL	Serial SSSS
	Datamatrix	Type&Ver TTTTTTTV	Lot number LLLLL	Serial SSSS	Date code WWYY	

Outline			
Pin table [mm]			
Pin	X	Y	Function
1	25,6	6,4	ACIn2
2	22,4	6,4	ACIn2
3	16	9,6	ACIn1
4	12,8	9,6	ACIn1
5	9,6	0	DC+Rect
6	9,6	3,2	DC+Rect
7	0	0	DC-Rect
8	0	3,2	DC-Rect
9	not assembled		
10	not assembled		
11	0	22,4	G11
12	0	25,6	DC-1
13	0	28,8	DC-1
14	0	32	G13
15	0	35,2	DC-2
16	0	38,4	DC-2
17	0	41,6	G15
18	0	44,8	DC-3
19	0	48	DC-3
20	9,6	48	Therm1
21	19,2	48	Therm2
22	28,8	48	G16
23	32	48	Ph3
24	32	44,8	Ph3
25	32	35,2	G14
26	32	32	Ph2
27	32	28,8	Ph2
28	32	19,2	G12
29	32	16	Ph1
30	32	12,8	Ph1
31	32	3,2	ACIn3
32	32	0	ACIn3
33	22,4	19,2	DC+Inv
34	22,4	16	DC+Inv
35	not assembled		

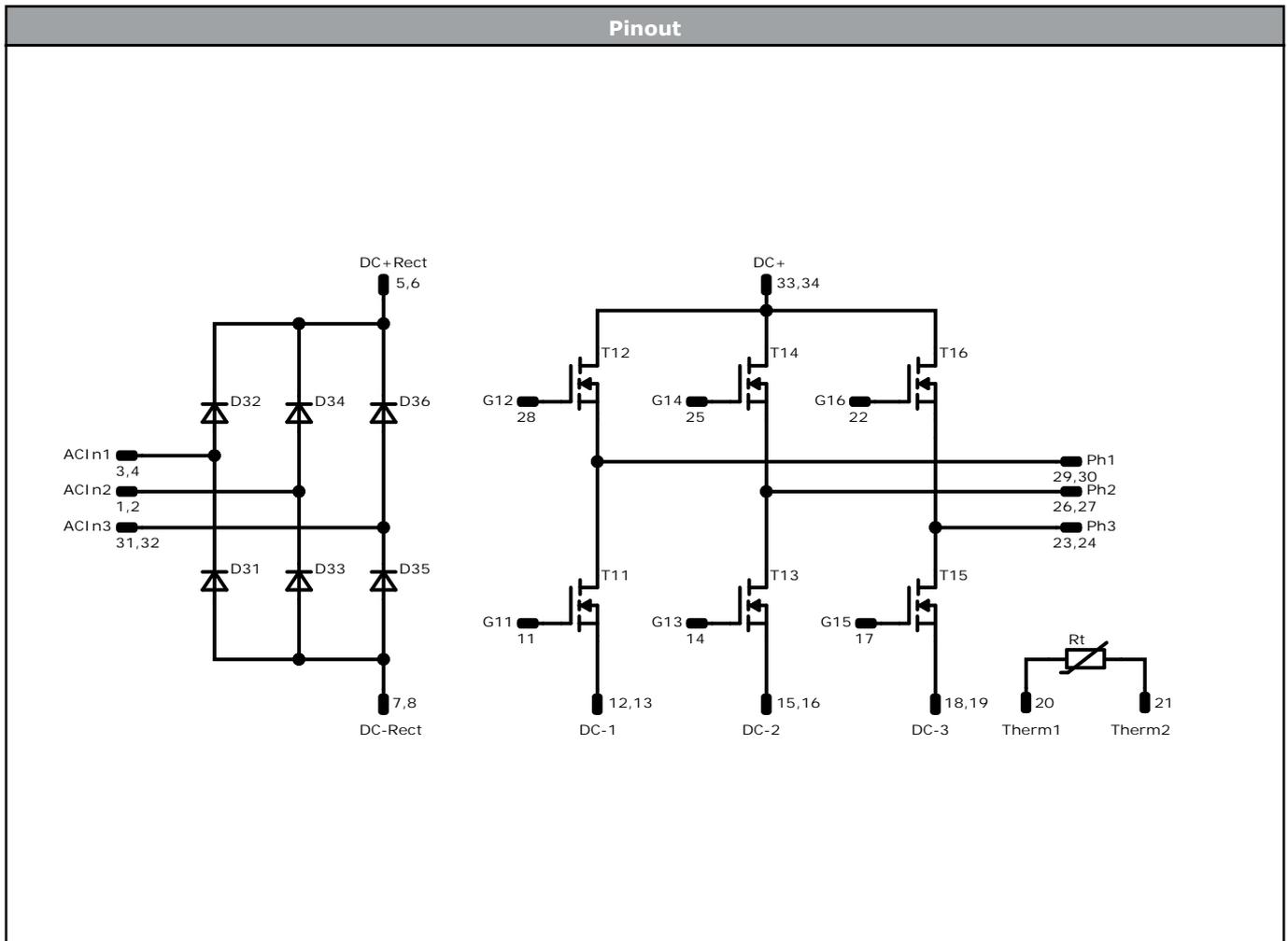


center of press-fit pinhead
for connection parameter see the handling instruction

Tolerance of positions: ±0.4mm at the end of pins
Dimension of coordinate axes is only offset without tolerance



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Identification					
ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	MOSFET	1200 V	32 mΩ	Inverter Switch	
D31, D32, D33, D34, D35, D36	Rectifier	1600 V	35 A	Rectifier Diode	
Rt	Thermistor			Thermistor	



Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for <i>flow</i> E2 packages see vincotech.com website.

Package data
Package data for <i>flow</i> E2 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
10-EY12PNA032ME02-L188C03T-D1-14	12 Jul. 2022		

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